

Title (en)
Copper plating bath

Title (de)
Kupferplattierungsbad

Title (fr)
Bain de déposition de cuivre

Publication
EP 1300487 A1 20030409 (EN)

Application
EP 01308482 A 20011004

Priority
US 97022401 A 20011002

Abstract (en)
A metal plating bath containing alcohol compounds that inhibit or retard the consumption of plating bath additives. The additives are chemical compounds that improve the brightness of the plated metal, the physical properties of the plated metal especially with respect to ductility and the micro-throwing power as well as the macro-throwing power of the plating bath. The alcohol compounds that inhibit or retard the consumption of additives increases the life of the plating bath and improves the efficiency of the plating process. The plating baths containing the alcohol compounds that inhibit or retard additive consumption can be employed to plate copper, gold, silver, palladium, platinum, cobalt, cadmium, chromium, bismuth, indium, rhodium, ruthenium, and iridium.

IPC 1-7
C25D 3/02; **C25D 3/38**

IPC 8 full level
C25D 3/02 (2006.01); **C25D 3/38** (2006.01); **C25D 17/10** (2006.01); **H05K 3/24** (2006.01)

CPC (source: EP KR US)
C25D 3/02 (2013.01 - EP US); **C25D 3/38** (2013.01 - EP KR US); **H05K 3/241** (2013.01 - EP US)

Citation (search report)

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EP 01308482 A 20011004; JP 2002289419 A 20021002; KR 20010079150 A 20011214; TW 90129378 A 20011128; US 72097203 A 20031124; US 97022401 A 20011002